

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHENG-CHUN YANG	03/03/2020
YI-MING LIN	03/03/2020
PO-WEI LIANG	03/04/2020
CHU-HAN HSIEH	03/03/2020
CHIH-LUNG CHENG	03/03/2020
PO-CHIH HUANG	03/03/2020
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16800220
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NAME OF SUBMITTER:	TAN T. TU
SIGNATURE:	/TAN T. TU/
DATE SIGNED:	03/17/2020
Total Attachments: 2	

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ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)_____

**METHOD FOR MANUFACTURING SEMICONDUCTOR WAFER WITH WAFER
CHUCK HAVING FLUID GUIDING STRUCTURE**

The PATENT RIGHTS referred to in this agreement are:

(check one) ☐ a patent application for this invention, executed by the ASSIGNOR(S)
concurrently with this assignment.

☒ U.S. patent application Serial No. 16/800,220, filed
February 25, 2020

☐ a U.S. patent application based on PCT International Application
No. _____ filed on (date) _____ (U.S. patent application
Serial No. _____, if known).

☐ U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of
the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

☒ U.S. patent rights only.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures
appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,
TAIWAN 300, R.O.C.

The ASSIGNEE is:

(check one) ☐ An individual.

☐ A Partnership.

☒ A Corporation of TAIWAN, R.O.C. (specify state or country)

☐ (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable
provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
 ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
 INVENTION TITLE: METHOD FOR MANUFACTURING SEMICONDUCTOR
WAFER WITH WAFER CHUCK HAVING FLUID GUIDING STRUCTURE

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Sheng-Chun YANG

Name of sole or first inventor

Sheng Chun YANG
Signature

2020.03.03
Date

Yi-Ming LIN

Name of second inventor, if any

Yi-Ming Lin
Signature

2020.03.03
Date

Po-Wei LIANG

Name of third inventor, if any

梁伯維 Po-wei Liang
Signature

2020.03.04
Date

Chu-Han HSIEH

Name of fourth inventor, if any

謝立翰 Chu-Han HSIEH
Signature

2020.03.03
Date

Chih-Lung CHENG

Name of fifth inventor, if any

鄭智龍 Chih-Lung Cheng
Signature

2020.3.3
Date

Po-Chih HUANG

Name of sixth inventor, if any

Po-Chih Huang
Signature

2020.03.03
Date